

# LNJ816C8DRU

## Surface Mounting Chip LED

MicroLens FD Type

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	60	mW
Forward current	$I_F$	20	mA
Pulse forward current *	$I_{FP}$	100	mA
Reverse voltage	$V_R$	3	V
Operating ambient temperature	$T_{opr}$	-30 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

### ■ Lighting Color

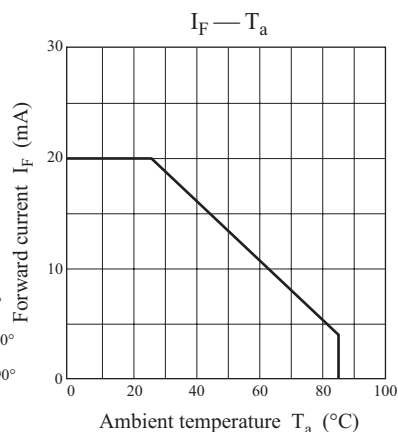
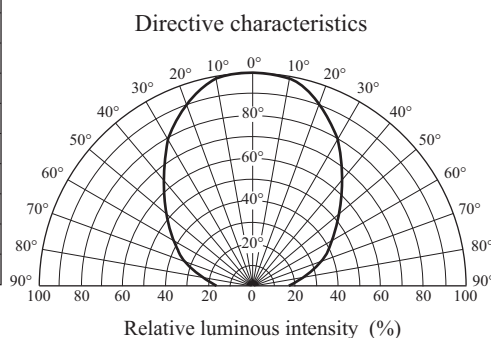
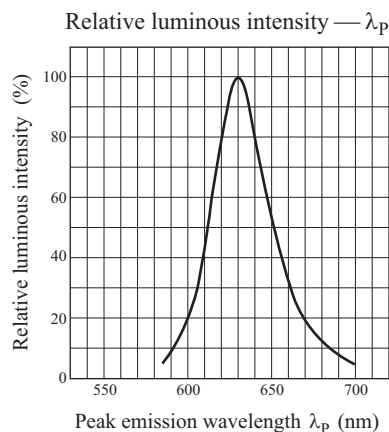
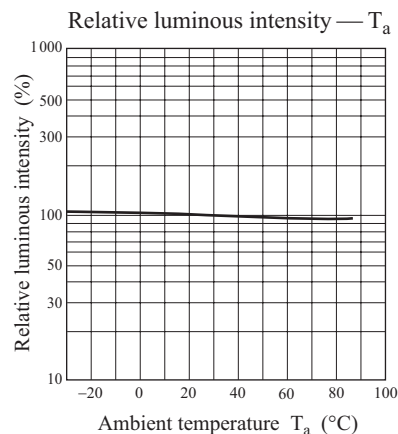
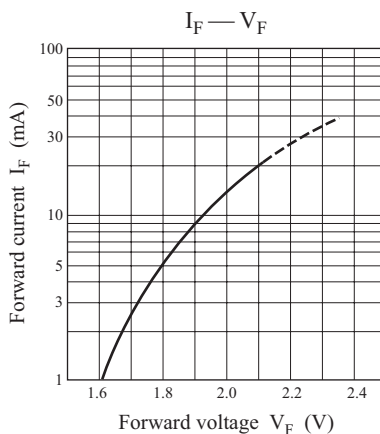
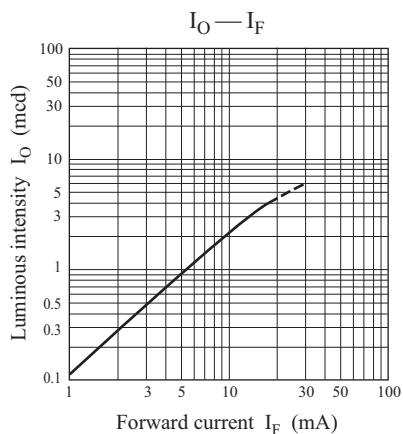
- Orange

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

### ■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

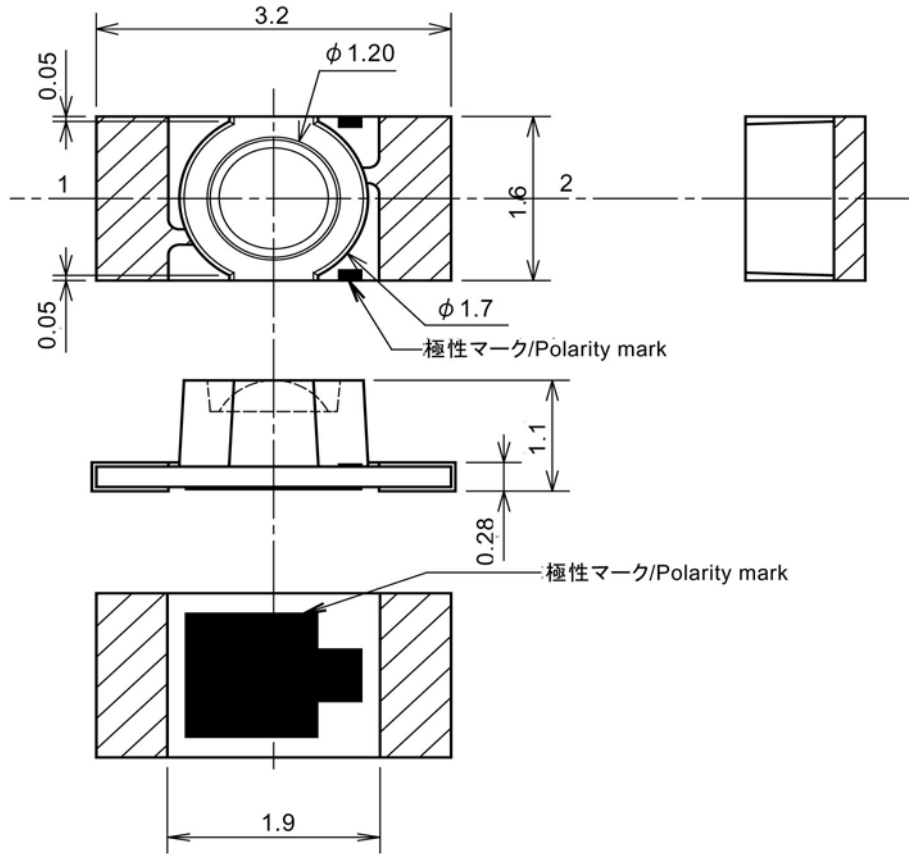
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	$I_O$	$I_F = 10 \text{ mA}$	1.1	2.1		mcd
Reverse current	$I_R$	$V_R = 3 \text{ V}$			10	$\mu\text{A}$
Forward voltage	$V_F$	$I_F = 10 \text{ mA}$		1.93	2.60	V
Peak emission wavelength	$\lambda_P$	$I_F = 10 \text{ mA}$		630		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10 \text{ mA}$		40		nm

Note) \*: Measurement tolerance:  $\pm 20\%$



■ Package (Unit: mm)

KLTLTN2K1600



- Pin name
- 1: Anode
- 2: Cathode

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